

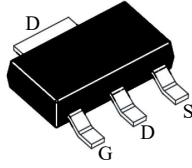


SMTQ06N750LSSEH

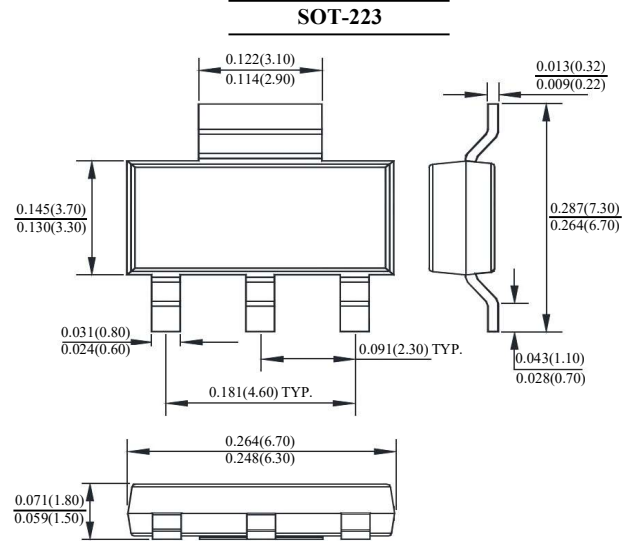
N-Channel Enhancement Mode Field Effect Transistor

FEATURES

· Suffix "H" indicates Halogen-free parts, ex.SMTQ06N750LSSEH



D	Drain
G	Gate
S	Source



Dimensions in inch and (millimeter)

Maximum Ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit	
Drain-Source Voltage	V_{DS}	60	V	
Gate-Source Voltage	V_{GS}	± 20	V	
Drain Current	I_D	$T_C = 25^\circ\text{C}$	4.0	A
		$T_C = 100^\circ\text{C}$	2.9	A
Pulsed Drain Current (Note 1)	I_{DM}	16	A	
Single-Pulse Avalanche Current	I_{AS}	5.4	A	
Single-Pulse Avalanche Energy (Note 2)	E_{AS}	1.5	mJ	
Power Dissipation	P_D	1.25	W	
Thermal Resistance from Junction to Ambient (Note 3)	$R_{\theta JA}$	100	$^\circ\text{C}/\text{W}$	
Thermal Resistance from Junction to Case	$R_{\theta JC}$	20	$^\circ\text{C}/\text{W}$	
Operating and Storage Temperature Range	T_J, T_{stg}	- 55 to + 150	$^\circ\text{C}$	

Note :

1. Pulse width $\leq 100\mu\text{s}$, Duty Cycle $\leq 2\%$, Repetitive rating, pulse width limited by junction temperature $T_{J(\text{MAX})} = 150^\circ\text{C}$.
2. Limited by $T_{J(\text{MAX})}$, starting $T_J = 25^\circ\text{C}$, $L = 0.1\text{mH}$, $R_g = 25\Omega$, $I_{AS} = 5.4\text{A}$, $V_{GS} = 10\text{V}$.
3. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate in still air. Steady state.



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Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Conditions	Symbol	Min.	Typ.	Max.	Unit
Static						
Drain Source Breakdown Voltage	$I_D = 250\mu\text{A}$	$V_{(BR)DSS}$	60	-	-	V
Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	$V_{GS(th)}$	1.2	-	2.5	V
Zero Gate Voltage Drain Current	$V_{DS} = 48\text{V}$	I_{DSS}	-	-	1	μA
Gate-Body Leakage Current	$V_{GS} = \pm 20\text{V}$	I_{GSS}	-	-	± 0.1	μA
Drain-Source On-State Resistance	$V_{GS} = 10\text{V}, I_D = 2\text{A}$	$R_{DS(on)}$	-	68	78	m Ω
	$V_{GS} = 4.5\text{V}, I_D = 1.5\text{A}$		-	-	100	
Dynamic						
Forward Transfer Admittance	$V_{DS} = 5\text{V}, I_D = 2\text{A}$	g_{FS}	-	3.9	-	S
Gate Resistance	$V_{GS} = 0\text{V}, V_{DS} = 0\text{V}, f = 1\text{MHz}$	R_g	-	0.9	-	Ω
Total Gate Charge	$V_{DS} = 30\text{V}, I_D = 3\text{A}, V_{GS} = 4.5\text{V}$	Q_g	-	4.3	-	nC
Gate-Source Charge			$V_{DS} = 30\text{V}, I_D = 3\text{A}, V_{GS} = 10\text{V}$	Q_{gs}	-	
Gate-Drain Charge	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	Q_{gd}	-	1.9	-	
Input Capacitance			C_{iss}	-	446.6	
Output Capacitance	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	C_{oss}	-	26.0	-	pF
Reverse Transfer Capacitance			C_{rss}	-	5.0	
Turn-On Delay Time	$V_{DS} = 30\text{V}, V_{GS} = 10\text{V}, I_D = 3\text{A}, R_g = 4.7\Omega$	$t_{d(on)}$	-	7	-	ns
Turn-On Rise Time		t_r	-	3	-	
Turn-Off Delay Time		$t_{d(off)}$	-	6	-	
Turn-Off Fall Time		t_f	-	2	-	
Drain-Source Body Diode						
Drain-Source Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 4\text{A}$	V_{SD}	-	-	1.2	V
Diode Continuous Forward Current	-	I_S	-	-	4	A
Diode Pulse Current	-	I_{SM}	-	-	16	A
Reverse Recovery Time	$I_S = 4\text{A}, di/dt = 100\text{A}/\mu\text{s}$	t_{rr}	-	8.4	-	ns
Reverse Recovery Charge		Q_{rr}	-	4.6	-	nC



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RATINGS AND CHARACTERISTIC CURVES

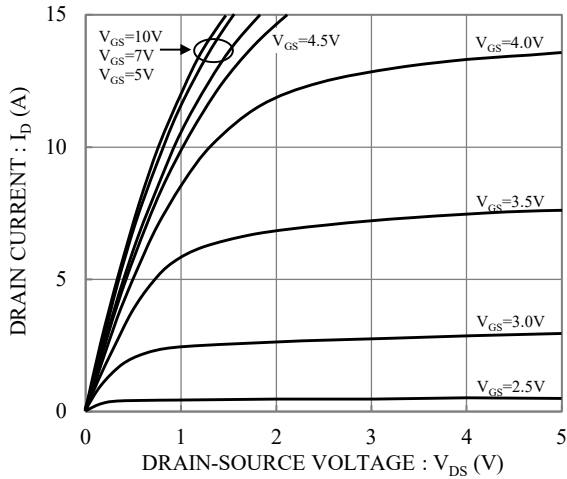


Fig.1 Typical Output Characteristics

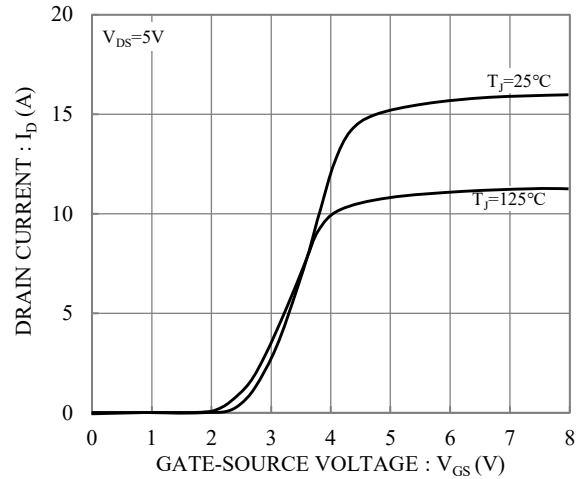


Fig.2 Typical Transfer Characteristics

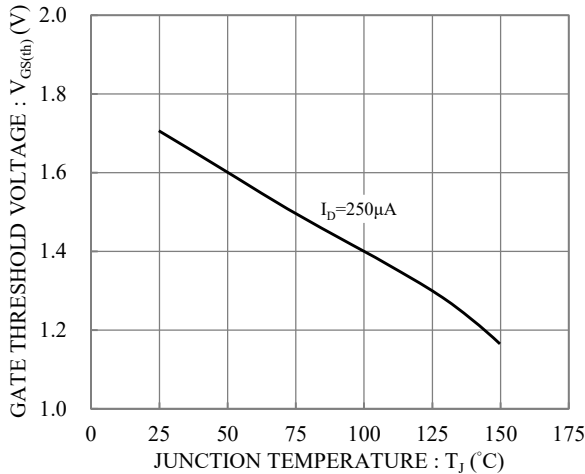


Fig.3 Gate Threshold Voltage vs. Junction Temperature

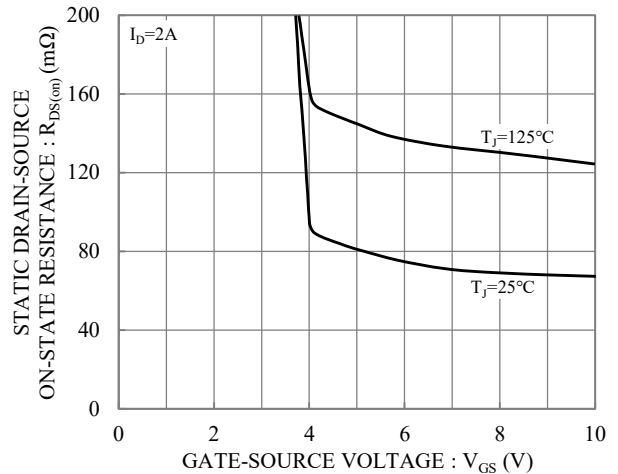


Fig.4 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

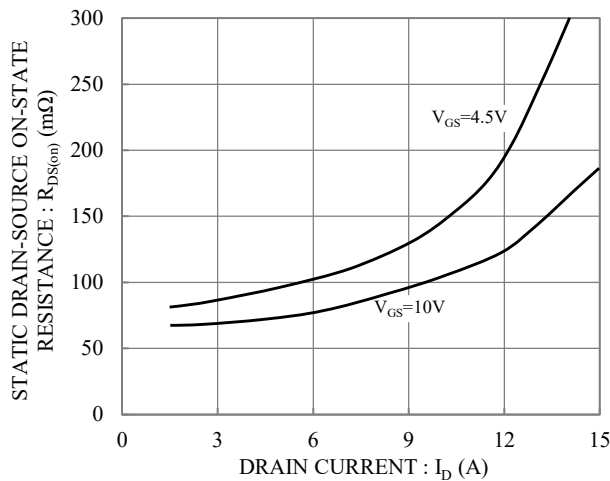


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

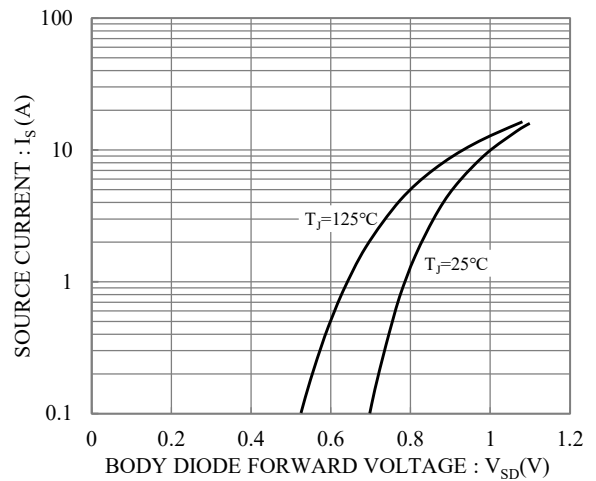


Fig.6 Body Diode Forward Voltage vs. Source Current



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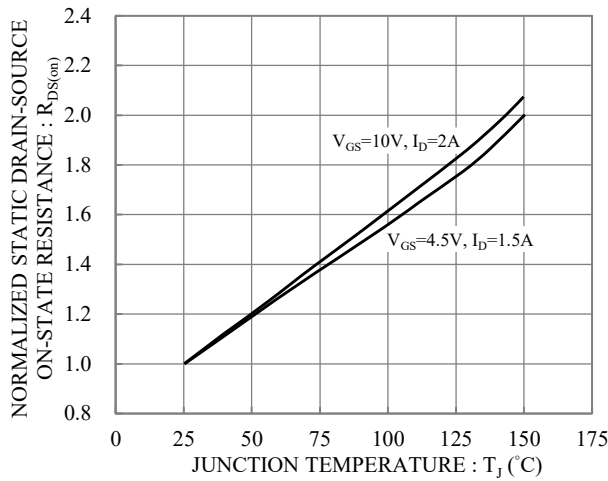


Fig.7 Drain-Source On-State Resistance vs. Junction Temperature

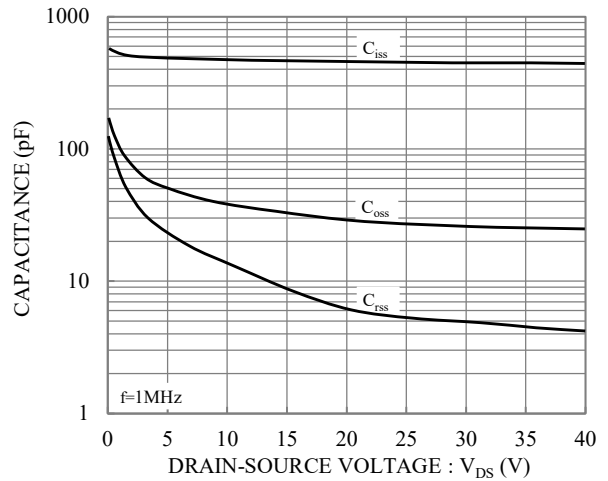


Fig.8 Capacitance vs. Drain-Source Voltage

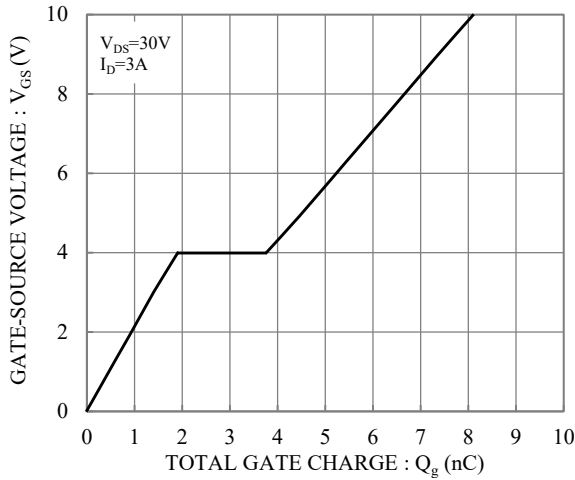


Fig.9 Gate Charge

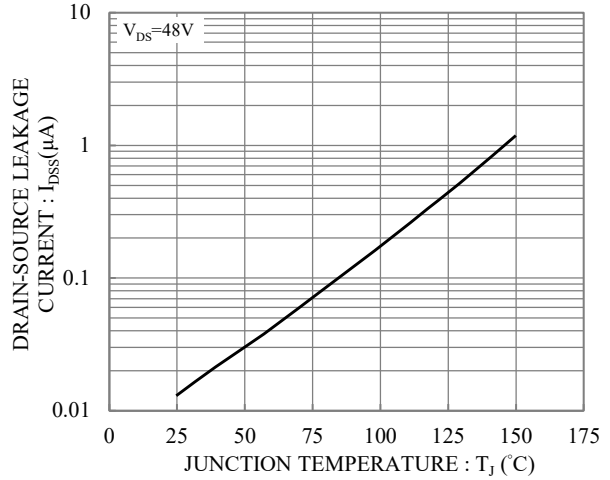


Fig.10 Drain-Source Leakage Current vs. Junction Temperature

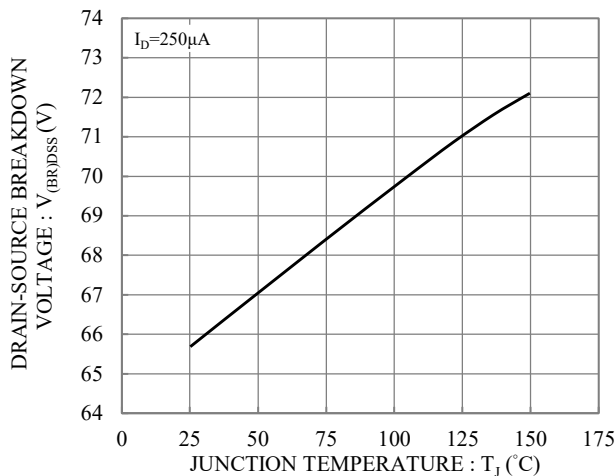


Fig.11 Breakdown Voltage vs. Junction Temperature

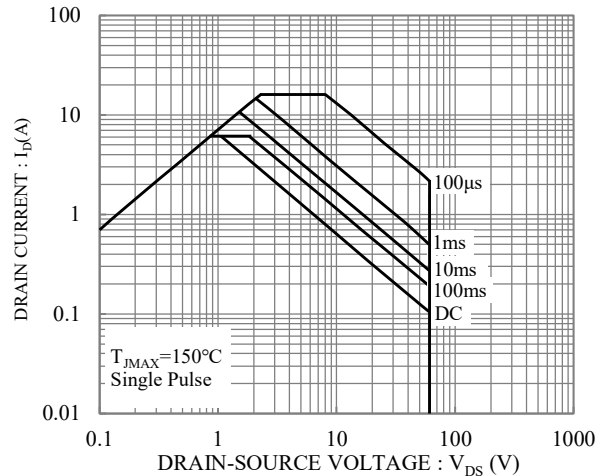


Fig.12 Safe Operation Area



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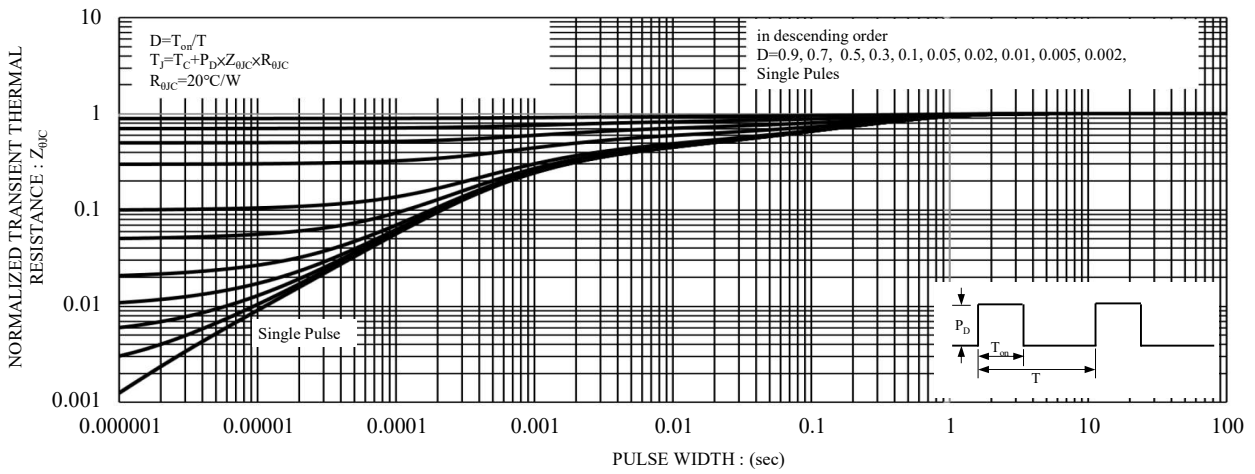


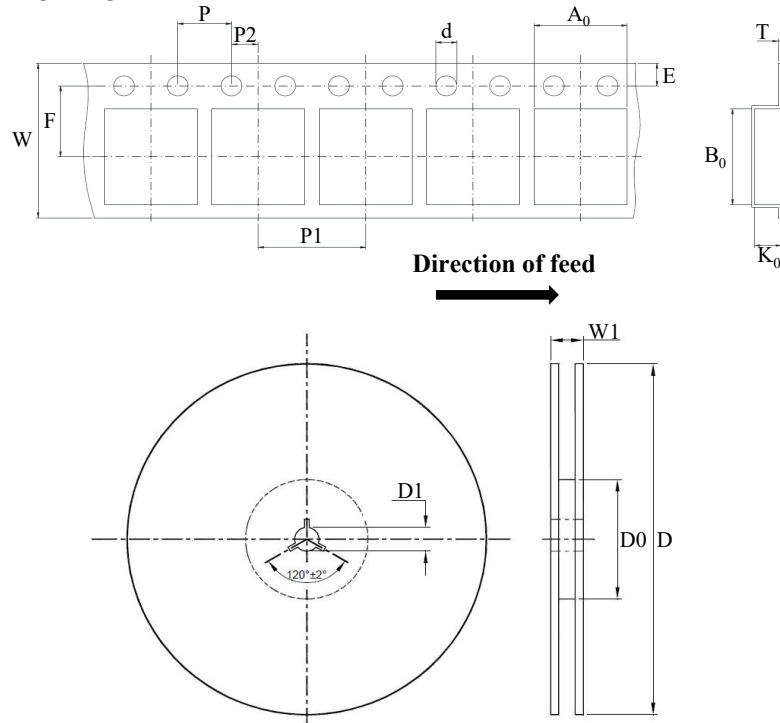
Fig.13 Maximum Transient Thermal Impedance



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TAPE & REEL SPECIFICATION



Item	Symbol	SOT-223
Carrier width	A ₀	7.05 ± 0.10
Carrier length	B ₀	7.45 ± 0.10
Carrier depth	K ₀	1.95 ± 0.10
Sprocket hole	d	1.50 ± 0.10
Reel outside diameter	D	330.00 ± 2.00
Feed hole width	D ₀	100.00
Reel inner diameter	D ₁	16.40 ± 0.50
Sprocke hole position	E	1.75 ± 0.10
Punch hole position	F	5.50 ± 0.10
Sprocke hole pitch	P ₀	4.00 ± 0.10
Punch hole pitch	P ₁	8.00 ± 0.10
Embossment center	P ₂	2.00 ± 0.10
Overall tape thickness	T	0.25 ± 0.05
Tape width	W	12.00 ± 0.20
Reel width	W1	MAX. 20.00

ORDER INFORMATION

Part Number	Marking Code	Reel Size	Quantity
SMTQ06N750LSSEH	TQ06N750LS	13"	3,000



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SUGGESTED SOLDER PAD LAYOUT

